



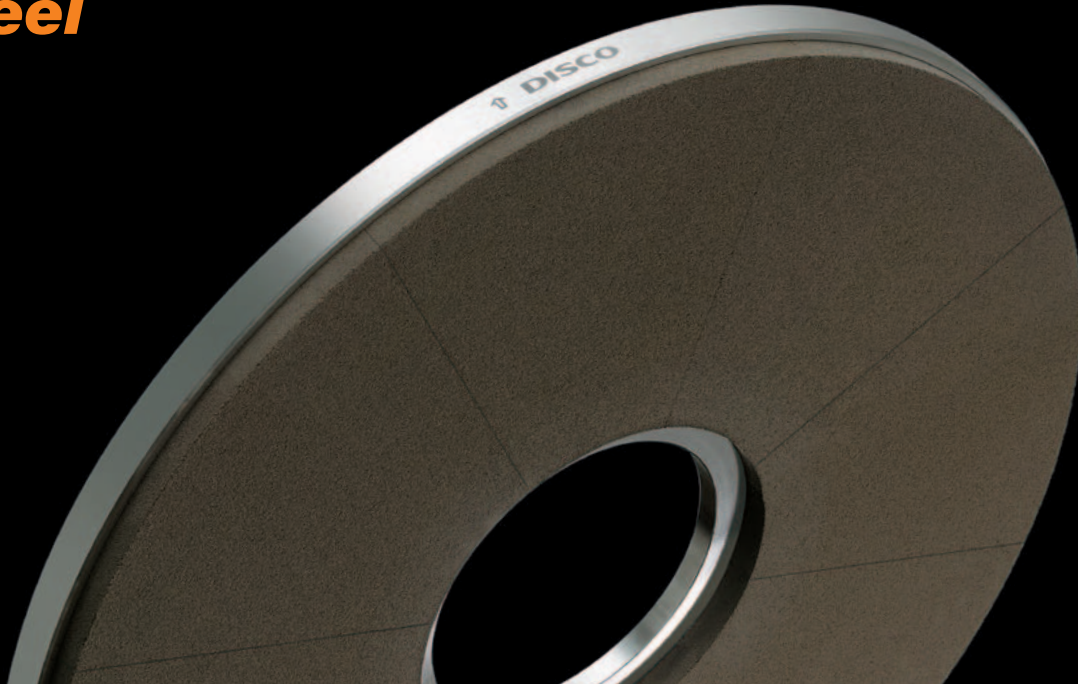
**DISCO**

Kiru · Kezuru · Migaku Technologies



# Dry Polishing Wheels DP08 SERIES

## Chemical free stress relief dry polishing wheel



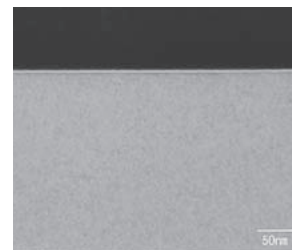
**In addition to wafer polishing in the conventional grinding process, the DP08 realizes chemical-free stress relief that can even be used with the DBG process.**

The DP08 Series enables polishing of ultra-thin wafers with DISCO's unique dry polishing process.

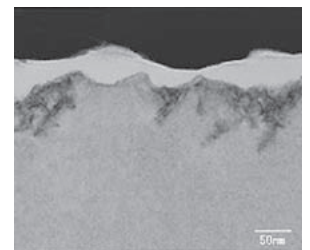
In addition to having a low environmental impact by not using chemicals, it achieves high die strength and is simple to operate compared to a process that uses slurry.

### ■ Damage comparison (Observed with a TEM)

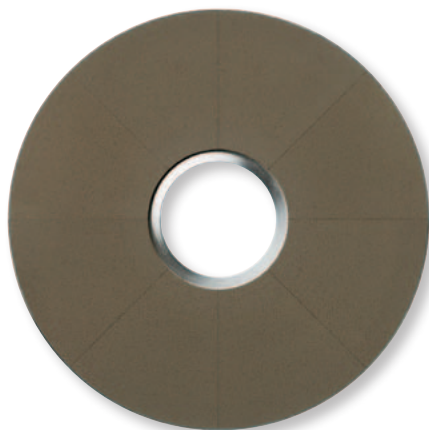
Damage has been removed from the wafer processed with dry polishing.



After DP08 polishing



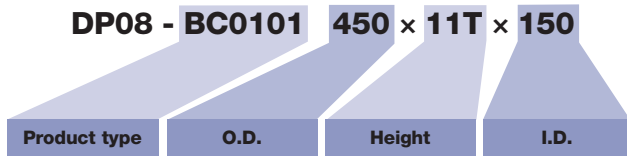
After #2000 grinding



### Applications

*Silicon wafers, etc.*

## Specifications

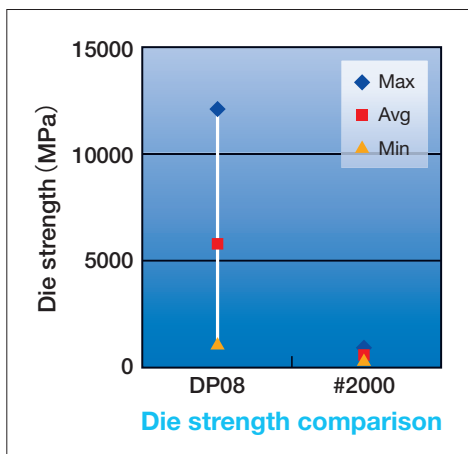


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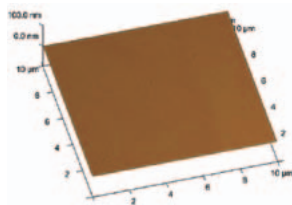
## Experimental Data

### Die Strength (Ball point breakage test)

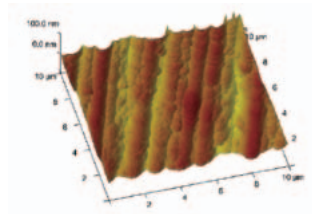


Workpiece : 8" Silicon wafer  
Final grinding thickness : 200  $\mu\text{m}$

### Surface roughness



DP08 Series



Grinding Wheel (#2000)

Ra ( $\mu\text{m}$ )	0.0003	0.0146
Ry ( $\mu\text{m}$ )	0.0017	0.0814

### When ordering

Please contact a DISCO representative with your product needs such as type, wheel size, and quantity.

When you place the first order with us, please explain application information such as materials to grind, sizes, machine, type, and other specification.

We are ready to help you to determine which is our most appropriate product type for your application.

Due to improvements in our products, it is possible that product specifications may be changed without advanced notice.  
Please confirm the product specifications with a DISCO representative.

### ⚠ To use these DISCO blades and wheels (hereafter precision tooling) safely... Please read carefully and follow the instructions below to prevent any accidents or injuries.

- USE a safety cover (nozzle case, cover), equipped as a standard accessory, to avoid injury.
- DO NOT EXCEED the specified rpm limit indicated on the precision tooling.
- FOLLOW the instruction manual of the equipment to mount the precision tooling properly.
- DO NOT DROP OR HIT the precision tooling. This may cause breakage or injury.
- Always CHECK the precision tooling for chipping or any other damage before starting to use it. DO NOT USE the tooling if there is any damage.
- READ the operation manual of the cutting/grinding equipment before use.
- DO NOT USE the precision tooling with modified or customized equipment.
- DO NOT USE precision tooling that has a different size from the one recommended for your equipment.
- DO NOT USE the precision tooling for any other purpose than grinding, cutting, or polishing.
- Always USE water or coolant to prevent precision tooling damage.



## DISCO CORPORATION

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